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Research Areas

Engineering and Technology

Published journal articles indexed by SCI, SSCI, and AHCI

- I. **Piezoelectric Multi-Channel Bilayer Transducer for Sensing and Filtering Ossicular Vibration**
YÜKSEL M. B., Atik A. C., KÜLAH H.
Advanced Science, vol.11, no.16, 2024 (SCI-Expanded)
- II. **Thin-Film PZT based Multi-Channel Acoustic MEMS Transducer for Cochlear Implant Applications**
Yüksel M. B., Koyuncuoglu A., Külah H.
IEEE Sensors Journal, vol.22, pp.3052-3060, 2022 (SCI-Expanded)
- III. **Single Supply PWM Fully Implantable Cochlear Implant Interface Circuit with Active Charge Balancing**
Yigit H. A., Ulsan H., Koc M., YÜKSEL M. B., Chamanian S., KÜLAH H.
IEEE Access, vol.9, pp.52642-52653, 2021 (SCI-Expanded)

Articles Published in Other Journals

- I. **A full-custom fully implantable cochlear implant system validated in vivo with an animal model**
ULUŞAN H., YÜKSEL M. B., TOPÇU O., Yiğit H. A., YILMAZ A. Ö., Doğan M., Gülhan Yasar N., Kuyumcu İ., Batu A., Göksu N., et al.
Communications Engineering, vol.3, no.1, 2024 (Scopus)
- II. **Multichannel multimodal piezoelectric middle ear implant concept based on MEMS technology for next-generation fully implantable cochlear implant applications**
Pirim F., Atik A. C., YÜKSEL M. B., Yılmaz A. M., UĞUR M. B., Tunah S., BATU A., ASLAN M. K., ÖZER M. B., KÜLAH H.
Biosensors and Bioelectronics: X, vol.18, 2024 (Scopus)

Refereed Congress / Symposium Publications in Proceedings

- I. **A Fully-Implantable Mems-Based Autonomous Cochlear Implant**

Klah H., Ulusah H., Chamanian S., Batu A., Uęur M. B., Yksel M. B., Yılmaz A. ., Yięit H., Koyuncuoglu A., Topęu ., et al.

35th IEEE International Conference on Micro Electro Mechanical Systems Conference, MEMS 2022, Tokyo, Japan, 9 - 13 January 2022, vol.2022-January, pp.396-399

II. Fabrication and Feasibility of Through Silicon Via for 3D MEMS Resonator Integration

Soydan A. K., Yksel M. B., Işık Akęakaya D., KLAH H.

18th IEEE Sensors Conference, Montreal, Canada, 27 - 30 October 2019

III. Multi-channel thin film piezoelectric acoustic transducer for cochlear implant applications

YKSEL M. B., Ilik B., Koyuncuoglu A., KLAH H.

18th IEEE Sensors Conference, Montreal, Canada, 27 - 30 October 2019

IV. A Pulse-Width Modulated Cochlear Implant Interface Electronics with 513 μ W Power Consumption

Yigit H. A., Ulsan H., YKSEL M. B., Chamanian S., Ciftci B., Koyuncuoglu A., Muhtarolu A., KLAH H.

IEEE/ACM International Symposium on Low Power Electronics and Design (ISLPED), Lausanne, Switzerland, 29 - 31 July 2019

Metrics

Publication: 9

Citation (WoS): 25

Citation (Scopus): 31

H-Index (WoS): 4

H-Index (Scopus): 4